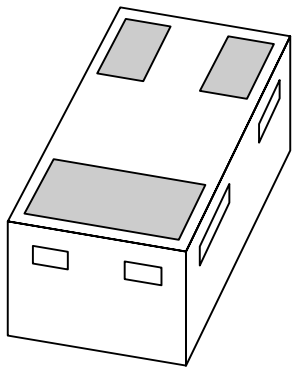


DATA SHEET



BAT54CM

Schottky barrier double diode

Schottky barrier double diode

BAT54CM

FEATURES

- Low forward voltage
- Leadless ultra small plastic package (1.0 × 0.6 × 0.5 mm)
- Boardspace 1.17 mm² (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Mobile communications, digital (still) cameras, PDAs and PCMCIA cards.

DESCRIPTION

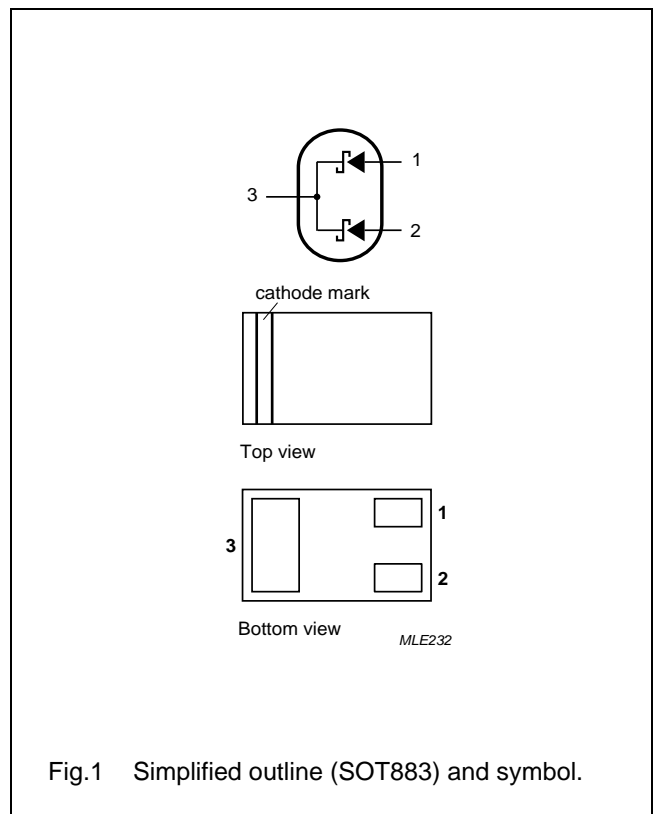
Planar Schottky barrier double diode encapsulated in a SOT883 leadless ultra small plastic package.

MARKING

TYPE NUMBER	MARKING CODE
BAT54CM	S3

PINNING

PIN	DESCRIPTION
1	anode (a ₁)
2	anode (a ₂)
3	common cathode



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAT54CM	–	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883

Schottky barrier double diode

BAT54CM

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	30	V
I_F	continuous forward current		–	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	–	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10$ ms	–	600	mA
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
P_{tot}	total power dissipation (per package)	$T_{amb} \leq 25$ °C; note 1	–	250	mW

Note

1. Refer to SOT883 standard mounting conditions (footprint); FR4 with 60 μ m copper strip line.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOT883 standard mounting conditions (footprint), FR4 with 60 μ m copper strip line.

Soldering

Reflow soldering is the only recommended soldering method.

ELECTRICAL CHARACTERISTICS

$T_{amb} = 25$ °C unless otherwise specified.

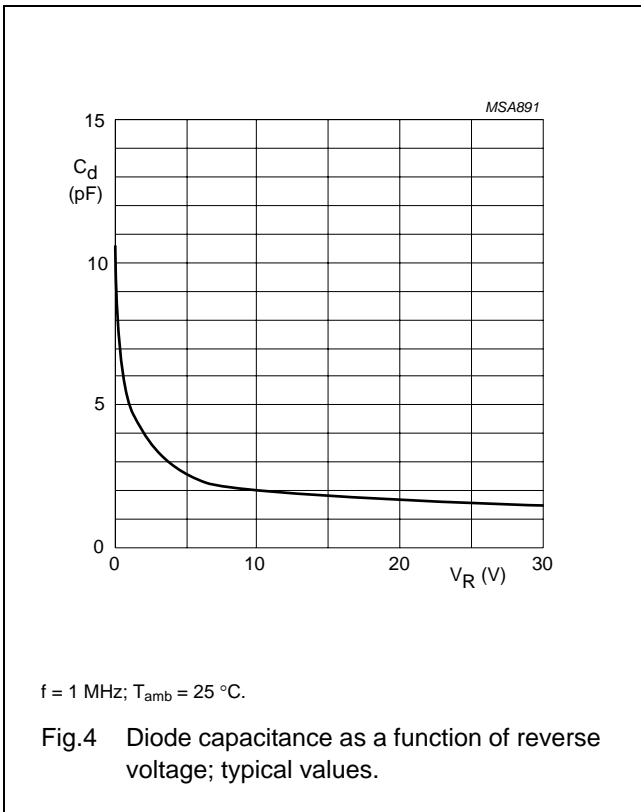
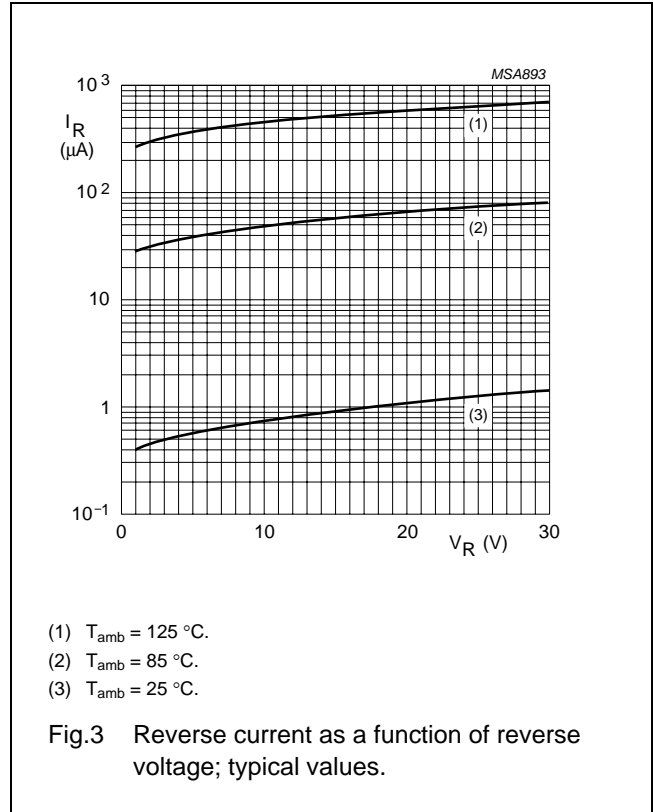
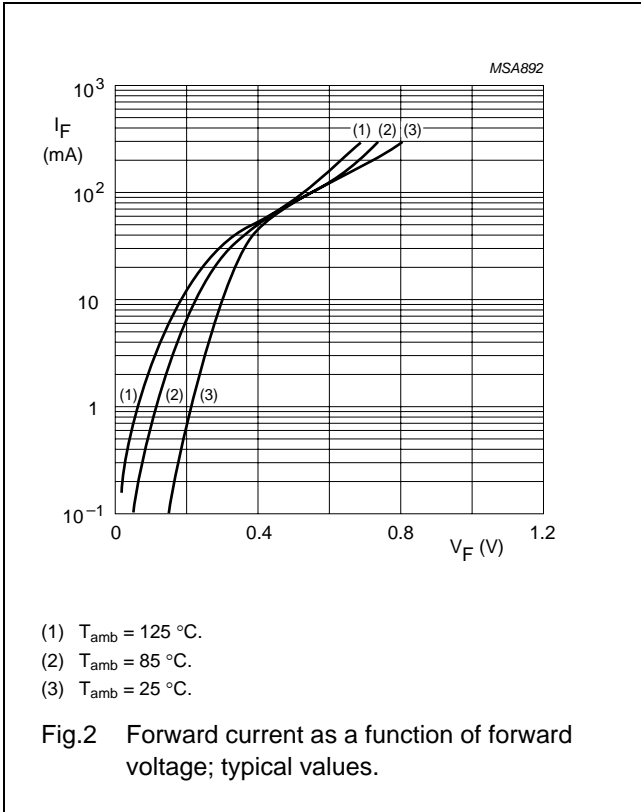
SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode				
V_F	forward voltage	see Fig.2; $I_F = 0.1$ mA $I_F = 1$ mA $I_F = 10$ mA $I_F = 30$ mA $I_F = 100$ mA	240 320 400 500 800	mV mV mV mV mV
I_R	continuous reverse current	$V_R = 25$ V; note 1; see Fig.3	2	μ A
C_d	diode capacitance	$f = 1$ MHz; $V_R = 1$ V; see Fig.4	10	pF

Note

1. Pulsed test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.

Schottky barrier double diode

BAT54CM



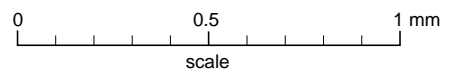
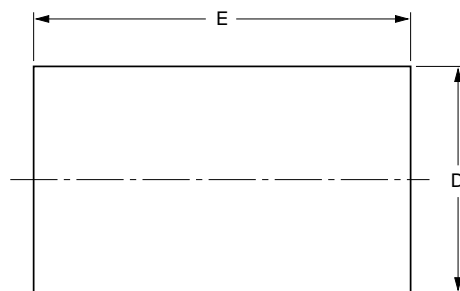
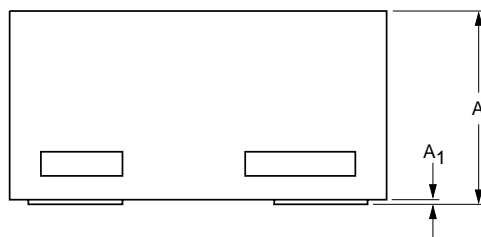
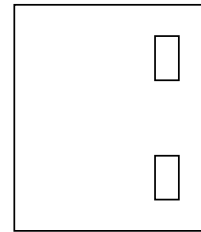
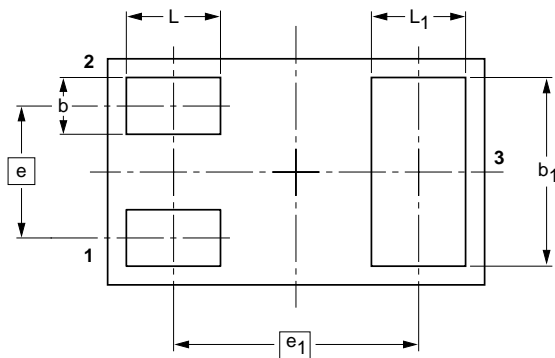
Schottky barrier double diode

BAT54CM

PACKAGE OUTLINE

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾	A ₁ max.	b	b ₁	D	E	e	e ₁	L	L ₁
mm	0.50 0.46	0.03	0.20 0.12	0.55 0.47	0.62 0.55	1.02 0.95	0.35	0.65	0.30 0.22	0.30 0.22

Note

1. Including plating thickness

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT883			SC-101			03-02-05 03-04-03

Schottky barrier double diode

BAT54CM

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

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